

B. In the Claims

Please cancel claims 20-24, without prejudice.

Please amend the claims as follows:

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1. (Amended) A test probe for a high-frequency device having an electronic circuit with two or more contact regions, the test probe comprising:
two or more signal probe tips, each signal probe tip having a contact surface area for contacting one of the contact regions of the device; and
a ground probe having a ground contact surface with a surface area substantially greater than the contact surface area of the one signal probe tip for contacting another one of the contact regions of the electronic circuit, wherein the ground contact surface is positioned between at least two of the signal probe tips.

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7. (Amended) The test probe of claim 1, wherein the device includes at least one DC contact region for receiving a DC bias input, and wherein the test probe further comprises at least one DC bias tip for contacting the one DC contact region and providing a DC bias signal.

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9. (Amended) The test probe of claim 1, wherein the electronic circuit is mounted on a work surface and one signal probe tip has a tip axis which defines a non-right angle with the work surface.

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10. (Amended) A test system for testing two or more microwave devices, with each device having at least one signal port, at least one ground pad, and at least one DC input-output pad, the system comprising:
a work surface for supporting the two or more microwave devices;
a test head including:
two or more signal probe tips, each signal probe tip having a contact surface area for contacting a signal port of a first one of the microwave devices;
a first ground probe having a ground contact surface with a contact surface area substantially greater than the contact surface area of the one signal probe tip

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for contacting the one ground pad of the first one of the microwave devices, wherein the first ground contact surface is positioned between at least two of the signal probe tips; and

programmable means for sequentially moving the test head into alignment with each of the microwave devices on the work surface and for bringing the signal probe tip into contact with the one signal port of each microwave device and the contact surface of the first ground probe into contact with the one ground pad of each microwave device.

Sub B' 15. (Amended) The test probe of claim 14, wherein the first and second signal probe tips have respective first and second contact areas; and

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the ground structure includes a ground contact area which is greater than at least one of the first and second contact areas.

Sub B' 17. (Amended) A method of testing microwave or high-frequency devices, with each device having at least one signal port, at least one ground pad, and at least one DC input-output pad, the method comprising:

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providing a test head comprising two or more signal probe tips, each probe tip having a contact surface area, and a first ground probe having a ground contact surface with a ground contact surface area substantially greater than the contact surface area of the one signal probe tip, the ground contact surface being positioned between at least two of the signal probe tips;

moving the contact surface of each of the signal probe tips into contact with a signal port of a first one of the devices and the contact surface of the first ground probe into contact with the one ground pad of the first one of the devices, thereby establishing a signal path between two of the signal probe tips positioned on opposite sides of the ground contact surface.

Sub B' 25. (Amended) A method of testing a device comprising a high-frequency electronic assembly having at least first and second conductive regions, the method comprising:

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providing a test head having first and second test-head contacts;
establishing electrical communication between the first test-head contact and the first conductive region and between the second test-head contact and the second conductive region;
sensing electrical communication between the first test-head contact and the first-head conductive region;
automatically introducing a test signal through the second test-head contact into the electronic assembly in response to sensing electrical communication between the first test-head contact and second conductive region.

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29. (Amended) For a surface-mount package having first and second signal ports and a ground pad between the signal ports, a method of establishing an electrical coupling of a predetermined nominal characteristic impedance with at least the first signal ports, the method comprising:

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- contacting the first signal port with a first electrical conductor;
- contacting the ground pad with a ground probe, with the ground probe having a ground contact and a surface overhanging a major surface of the signal port and being substantially parallel to the major surface; and
- adjusting the depth of the ground contact thereby positioning the overhanging portion of the ground probe a predetermined distance from the first signal port and establishing a predetermined impedance of the first signal port.
